

5

4

3

2

1

Notes/Revision Information

V0.01 - Initial Release

V0.02 - Updated R27 resistor value to 10K  
- Updated R43 resistor value to DNP

- 01 - Title Page
- 02 - MCU
- 03 - AFE031
- 04 - Passive Filters
- 05 - Power
- 06 - Connector

D

D

C

C

B

B

A

A

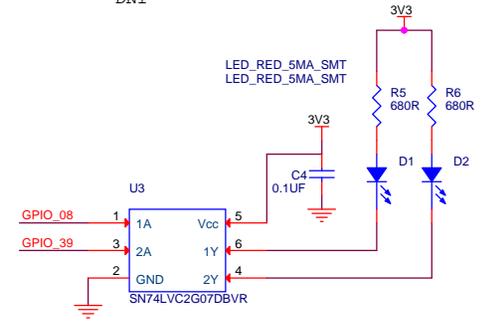
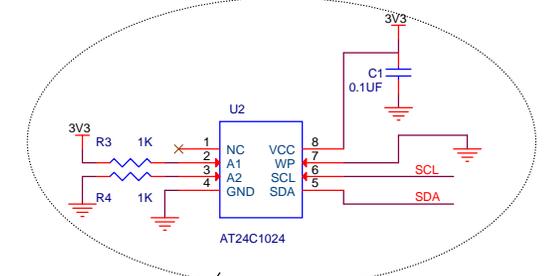
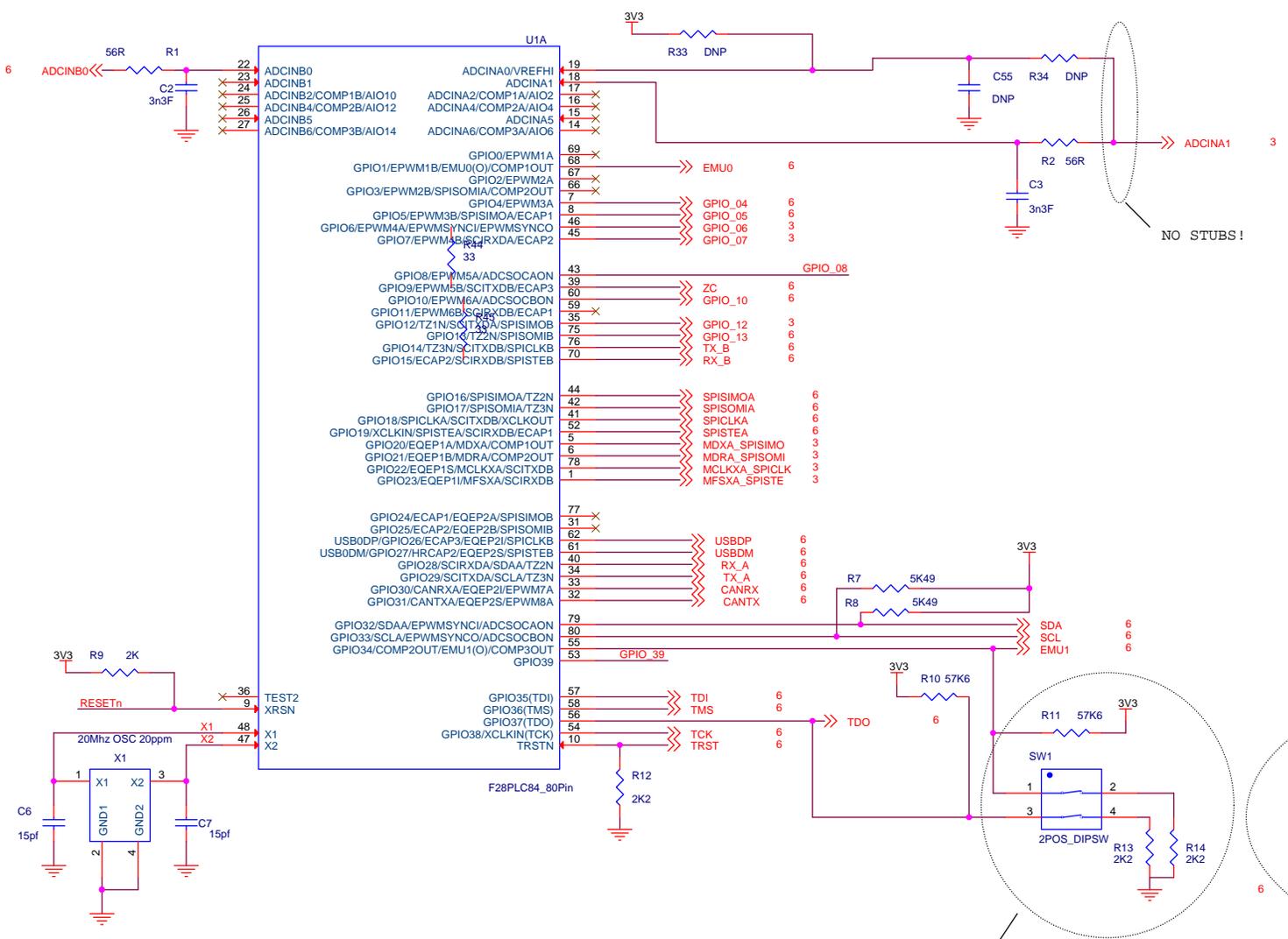
5

4

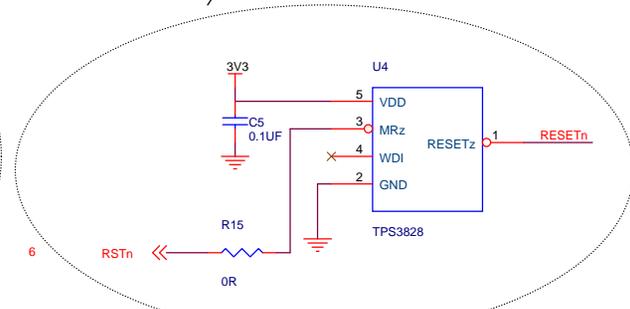
3

2

1

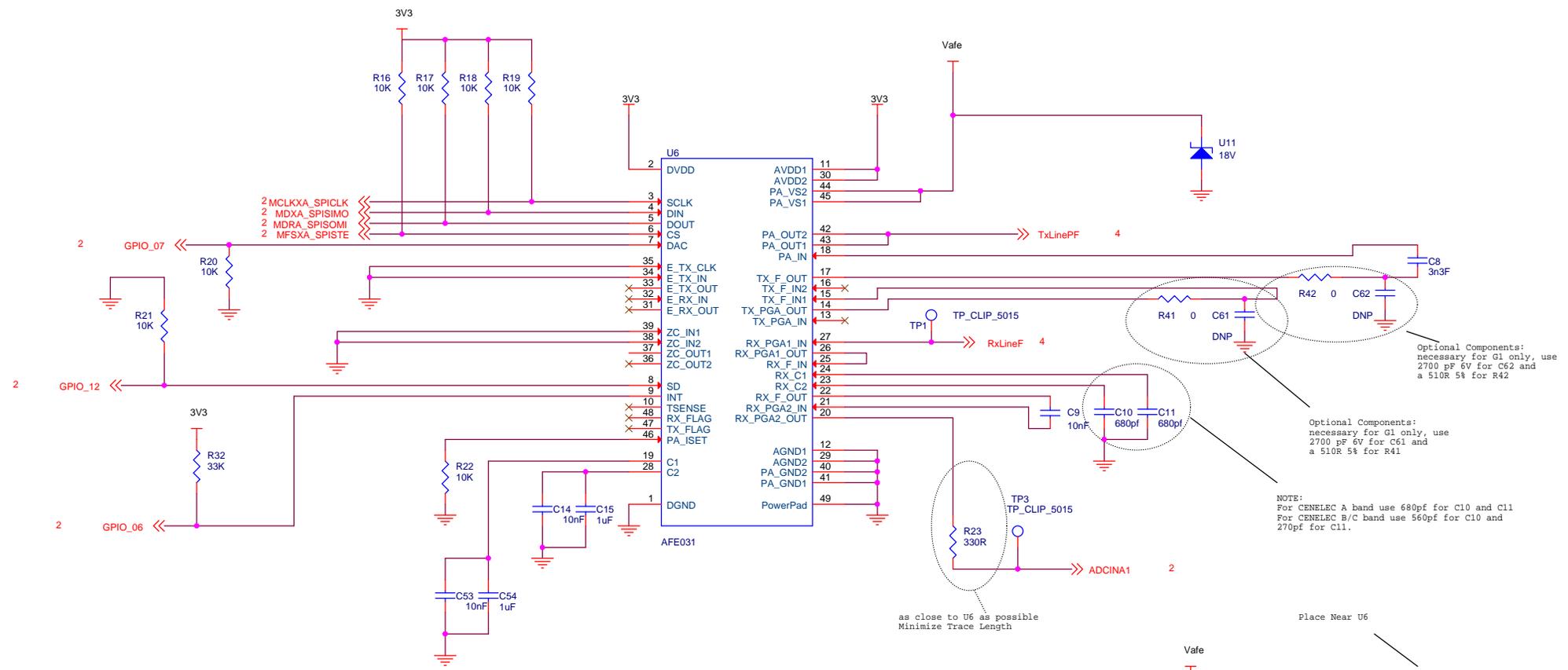


OPTIONAL if BOR is handled by the system or Host processor



Bootmode selection can be hard wired if required modes are known.

<b>TI</b>	
Page Contents: 02 - MCU	Revision: 0.18
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U6 MUST BE on TOP (OUTER, FREE-AIR) side of board!!!!

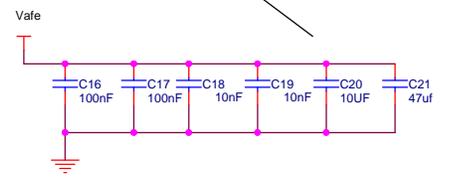
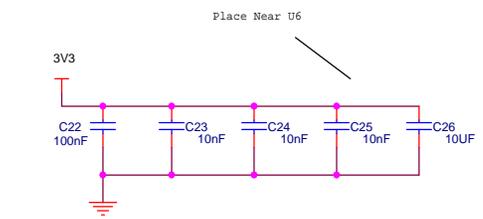
Optional Components:  
necessary for G1 only, use  
2700 pF 6V for C62 and  
a 510R 5% for R42

Optional Components:  
necessary for G1 only, use  
2700 pF 6V for C61 and  
a 510R 5% for R41

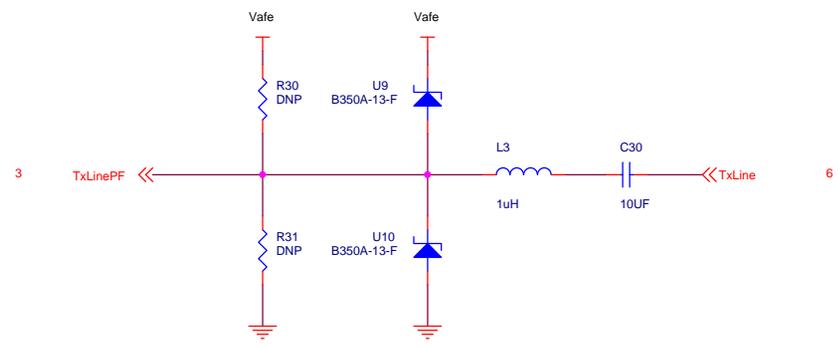
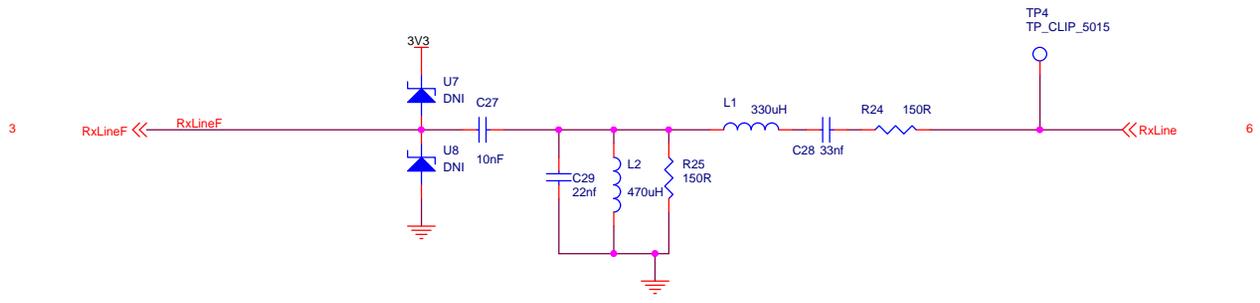
NOTE:  
For CENELEC A band use 680pf for C10 and C11  
For CENELEC B/C band use 560pf for C10 and  
270pf for C11.

as close to U6 as possible  
Minimize Trace Length

Place Near U6



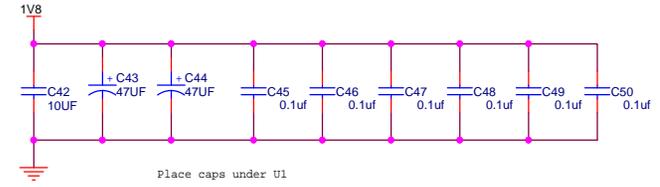
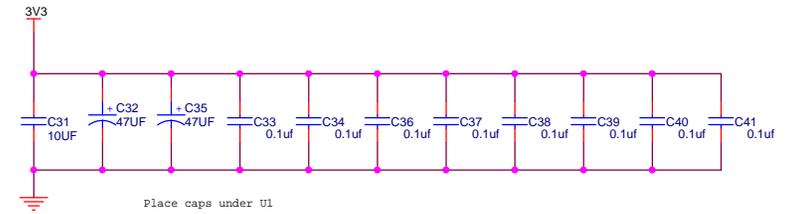
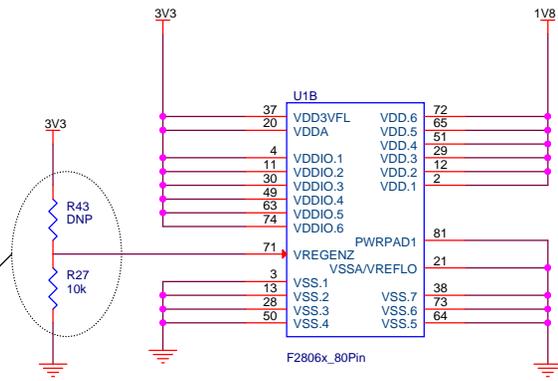
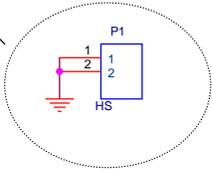
<b>TI</b>		<b>Title:</b> TIDM-SOMPLC-F28PLC84 MODULE	
		<b>Page Contents:</b> 03 - AFE031	
<b>Size:</b> B	<b>&lt;Doc&gt;</b>	<b>Revision:</b> 0.18	
<b>Date:</b> Monday, March 16, 2015	<b>Sheet 3 of 6</b>		



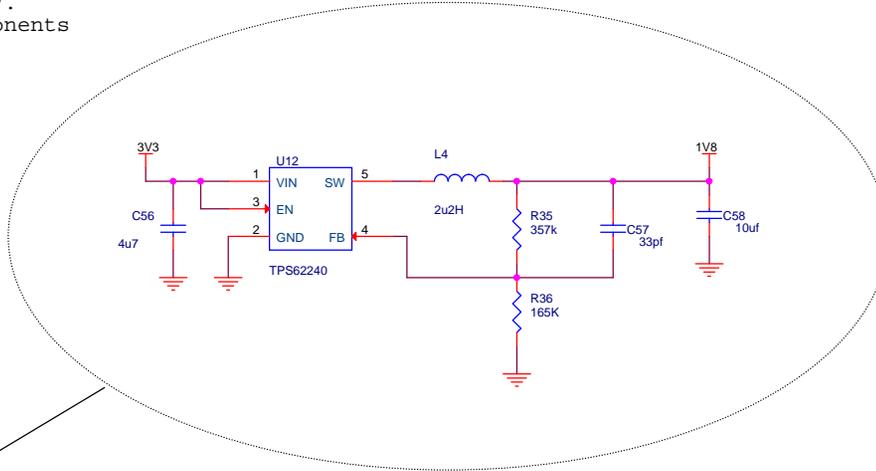
NOTE: Several components on this page have been removed or changed in the BOM.

<b>TI</b>	
Title: TIDM-SOMPLC-F28PLC84 MODULE	
Page Contents: 04 - AFE1 (Passive RX Filter)	
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OPTIONAL: Heatsink is not needed.



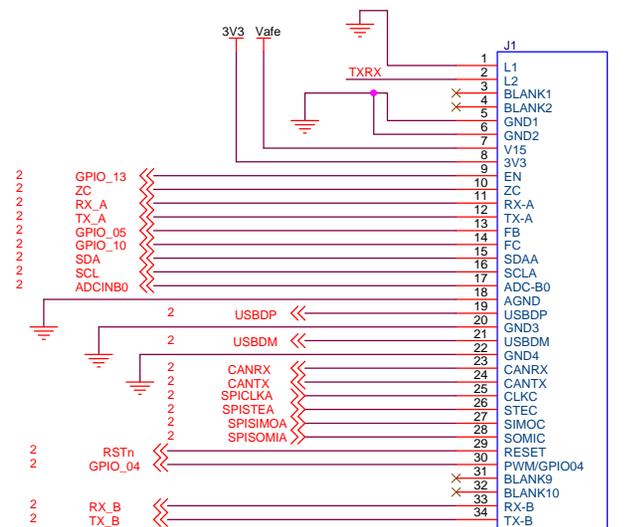
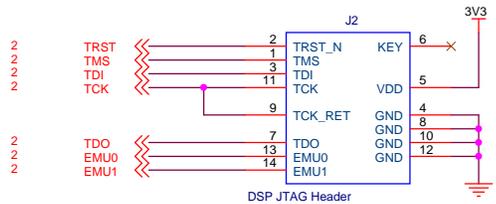
OPTIONAL: to source VDD with the on chip LDO, do not populate R43 and place a 10k resistor on R27. Additionally, the optional components below are not needed.



OPTIONAL: For reduced power consumption use a DC/DC converter instead of the On-Chip Linear Supply

Note: Follow Layout Procedures described in TPS62240 Datasheet

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Title: TIDM-SOMPLC-F28PLC84 MODULE	
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<b>TI</b>	
Title: TIDM-SOMPLC-F28PLC84 MODULE	
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